

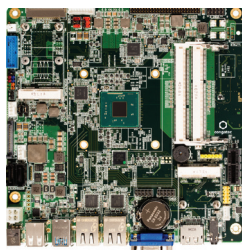
Modules vs. Down Board DRAM

Highly Ruggedized for Mission-Critical Environments

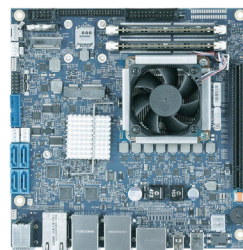
Reasons for transitioning to SMART Modules now

- Scalability (density and speed)
- Board space
- Thermal management
- Ease of routing
- Signal integrity
- Design flexibility
- Ruggedization
- Reliability
- Environmental protection
- Qualification

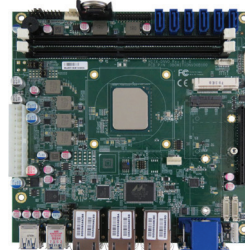
Successful Use Case Examples



SO-DIMMs

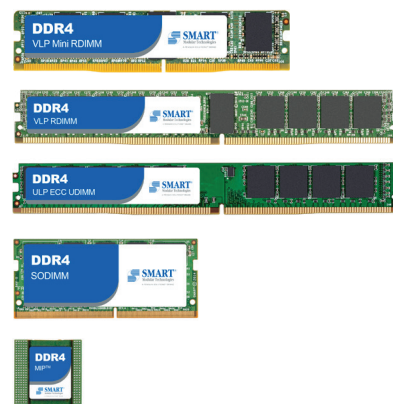
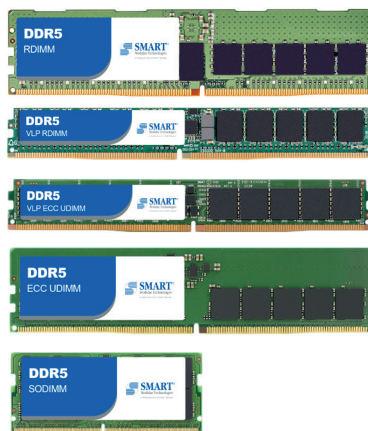


Mini-DIMMs



DIMMs and VLP DIMMs

DDR5 and DDR4 Modules



For more information, please visit: www.smartm.com

**Product images are for promotional purposes only. Labels may not be representative of the actual product.*

Headquarters/North America:

T: (+1) 800-956-7627 • T: (+1) 510-623-1231
F: (+1) 510-623-1434 • E: info@smartm.com

Latin America:

T: (+55) 11 4417-7200 • E: sales.br@smartm.com

Asia/Pacific:

T: (+65) 6678-7670 • E: sales.asia@smartm.com

EMEA:

T: (+44) 0 7826-064-745 • E: sales.euro@smartm.com

Customer Service:

T: (+1) 510-623-1231 • E: customers@smartm.com